

**BOND CLAMPS**  
**DESCRIPTION AND USE**

**1. GENERAL**

- 1.001** This addendum supplements Section 081-852-118, Issue 1.
- 1.002** It is issued to add information regarding placing of bonding devices.

**2. DESCRIPTION**

The following change applies to part 2 of this section:

- (a) 2.01 — added note
- 2.01** Add at the end of this paragraph.

**NOTE:** The core wrap which protects the conductors shall not be removed until the appropriate bonding device has been placed.